

# MO9121

## 1-220 MHz High Performance Differential Oscillator

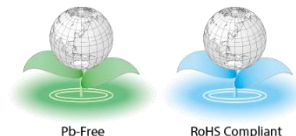


### Features

- Any frequency between 1 MHz and 220 MHz accurate to 6 decimal places
- LVPECL and LVDS output signaling types
- 0.6ps RMS phase jitter (random) over 12 kHz to 20 MHz bandwidth
- Frequency stability as low as  $\pm 10$  ppm
- Industrial and extended commercial temperature ranges
- Industry-standard packages: 3.2x2.5, 5.0x3.2 and 7.0x5.0 mmxmm
- For frequencies higher than 220 MHz, refer to MO9122 datasheet

### Applications

- 10GB Ethernet, SONET, SATA, SAS, Fibre Channel, PCI-Express
- Telecom, networking, instrumentation, storage, servers



### Electrical Characteristics

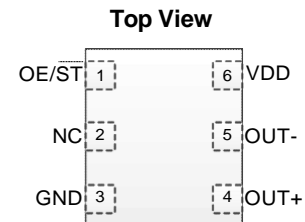
Parameter and Conditions	Symbol	Min.	Typ.	Max.	Unit	Condition
<b>LVPECL and LVDS, Common Electrical Characteristics</b>						
Supply Voltage	V <sub>dd</sub>	+2.97	+3.3	+3.63	V	Termination schemes in Figures 1 and 2 - XX ordering code
		+2.25	+2.5	+2.75	V	
		+2.25	–	+3.63	V	
Output Frequency Range	f	1	–	220	MHz	
Frequency Stability	F <sub>stab</sub>	-10	–	+10	ppm	Inclusive of initial tolerance, operating temperature, rated power supply voltage, and load variations
		-20	–	+20	ppm	
		-25	–	+25	ppm	
		-50	–	+50	ppm	
First Year Aging	F <sub>aging1</sub>	-2.0	–	+2.0	ppm	+25°C
10-year Aging	F <sub>aging10</sub>	-5.0	–	+5.0	ppm	+25°C
Operating Temperature Range	T <sub>use</sub>	-40	–	+85	°C	Industrial
		-20	–	+70	°C	Extended Commercial
Input Voltage High	V <sub>IH</sub>	70%	–	–	V <sub>dd</sub>	Pin 1, OE or $\overline{ST}$
Input Voltage Low	V <sub>IL</sub>	–	–	30%	V <sub>dd</sub>	Pin 1, OE or $\overline{ST}$
Input Pull-up Impedance	Z <sub>in</sub>	–	100	250	k $\Omega$	Pin 1, OE logic high or logic low, or $\overline{ST}$ logic high
		2.0	–	–	M $\Omega$	Pin 1, $\overline{ST}$ logic low
Start-up Time	T <sub>start</sub>	–	6.0	10	ms	Measured from the time V <sub>dd</sub> reaches its rated minimum value.
Resume Time	T <sub>resume</sub>	–	6.0	10	ms	In Standby mode, measured from the time $\overline{ST}$ pin crosses 50% threshold.
Duty Cycle	DC	45	–	55	%	Contact KDS for tighter dutycycle
<b>LVPECL, DC and AC Characteristics</b>						
Current Consumption	I <sub>dd</sub>	–	+61	+69	mA	Excluding Load Termination Current, V <sub>dd</sub> = +3.3V or +2.5V
OE Disable Supply Current	I <sub>OE</sub>	–	–	+35	mA	OE = Low
Output Disable Leakage Current	I <sub>leak</sub>	–	–	+1.0	$\mu$ A	OE = Low
Standby Current	I <sub>std</sub>	–	–	+100	$\mu$ A	$\overline{ST}$ = Low, for all V <sub>dds</sub>
Maximum Output Current	I <sub>driver</sub>	–	–	+30	mA	Maximum average current drawn from OUT+ or OUT-
Output High Voltage	V <sub>OH</sub>	V <sub>dd</sub> -1.1	–	V <sub>dd</sub> -0.7	V	See Figure 1(a)
Output Low Voltage	V <sub>OL</sub>	V <sub>dd</sub> -1.9	–	V <sub>dd</sub> -1.5	V	See Figure 1(a)
Output Differential Voltage Swing	V <sub>Swing</sub>	+1.2	+1.6	+2.0	V	See Figure 1(b)
Rise/Fall Time	T <sub>r</sub> , T <sub>f</sub>	–	300	700	ps	20% to 80%, see Figure 1(a)
OE Enable/Disable Time	T <sub>oe</sub>	–	–	115	ns	f = 212.5 MHz - For other frequencies, T <sub>oe</sub> = 100ns + 3 period
		–	1.2	1.7	ps	f = 100 MHz, V <sub>dd</sub> = +3.3V or +2.5V
		–	1.2	1.7	ps	f = 156.25 MHz, V <sub>dd</sub> = +3.3V or +2.5V
RMS Period Jitter	T <sub>jitt</sub>	–	1.2	1.7	ps	f = 212.5 MHz, V <sub>dd</sub> = +3.3V or +2.5V
		–	1.2	1.7	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V <sub>dds</sub>
RMS Phase Jitter (random)	T <sub>phj</sub>	–	0.6	0.85	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V <sub>dds</sub>
<b>LVDS, DC and AC Characteristics</b>						
Current Consumption	I <sub>dd</sub>	–	+47	+55	mA	Excluding Load Termination Current, V <sub>dd</sub> = +3.3V or +2.5V
OE Disable Supply Current	I <sub>OE</sub>	–	–	+35	mA	OE = Low
Differential Output Voltage	V <sub>OD</sub>	+250	+350	+450	mV	See Figure 2

### Electrical Characteristics (continued)

Parameter and Conditions	Symbol	Min.	Typ.	Max.	Unit	Condition
<b>LVDS, DC and AC Characteristics (continued)</b>						
Output Disable Leakage Current	I <sub>leak</sub>	–	–	+1.0	μA	OE = Low
Standby Current	I <sub>std</sub>	–	–	+100	μA	$\overline{ST}$ = Low, for all V <sub>dds</sub>
VOD Magnitude Change	ΔVOD	–	–	+50	mV	See Figure 2
Offset Voltage	VOS	+1.125	+1.2	+1.375	V	See Figure 2
VOS Magnitude Change	ΔVOS	–	–	+50	mV	See Figure 2
Rise/Fall Time	T <sub>r</sub> , T <sub>f</sub>	–	495	700	ps	20% to 80%, see Figure 2
OE Enable/Disable Time	T <sub>oe</sub>	–	–	115	ns	f = 212.5 MHz - For other frequencies, T <sub>oe</sub> = 100ns + 3 period
RMS Period Jitter	T <sub>jitt</sub>	–	1.2	1.7	ps	f = 100 MHz, V <sub>dd</sub> = +3.3V or +2.5V
		–	1.2	1.7	ps	f = 156.25 MHz, V <sub>dd</sub> = +3.3V or +2.5V
		–	1.2	1.7	ps	f = 212.5 MHz, V <sub>dd</sub> = +3.3V or +2.5V
RMS Phase Jitter (random)	T <sub>phj</sub>	–	0.6	0.85	ps	f = 156.25 MHz, Integration bandwidth = 12 kHz to 20 MHz, all V <sub>dds</sub>

### Pin Description

Pin	Map	Functionality
1	OE	Input H or Open: specified frequency output L: output is high impedance
	$\overline{ST}$	Input H or Open: specified frequency output L: Device goes to sleep mode. Supply current reduces to I <sub>std</sub> .
2	NC	NA No Connect; Leave it floating or connect to GND for better heat dissipation
3	GND	Power VDD Power Supply Ground
4	OUT+	Output Oscillator output
5	OUT-	Output Complementary oscillator output
6	VDD	Power Power supply voltage



### Absolute Maximum

Attempted operation outside the absolute maximum ratings may cause permanent damage to the part. Actual performance of the IC is only guaranteed within the operational specifications, not at absolute maximum ratings.

Parameter	Min.	Max.	Unit
Storage Temperature	-65	+150	°C
VDD	-0.5	+4.0	V
Electrostatic Discharge (HBM)	–	+2000	V
Soldering Temperature (follow standard Pb free soldering guidelines)	–	+260	°C

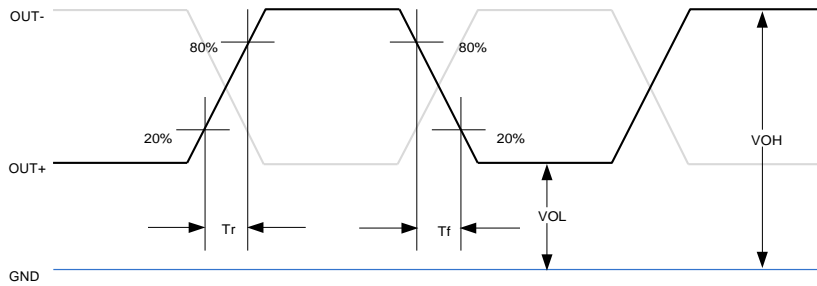
### Thermal Consideration

Package	θ <sub>JA</sub> , 4 Layer Board (°C/W)	θ <sub>JC</sub> , Bottom (°C/W)
7050, 6-pin	142	27
5032, 6-pin	97	20
3225, 6-pin	109	20

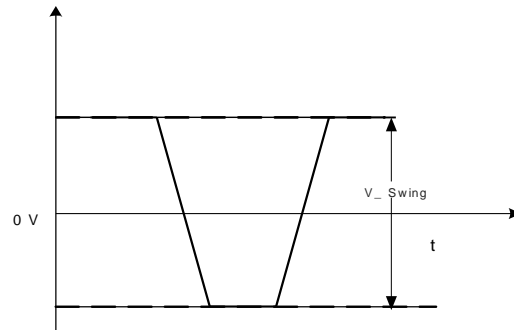
### Environmental Compliance

Parameter	Condition/Test Method
Mechanical Shock	MIL-STD-883F, Method2002
Mechanical Vibration	MIL-STD-883F, Method2007
Temperature Cycle	JESD22, Method A104
Solderability	MIL-STD-883F, Method2003
Moisture Sensitivity Level	MSL1 @ 260°C

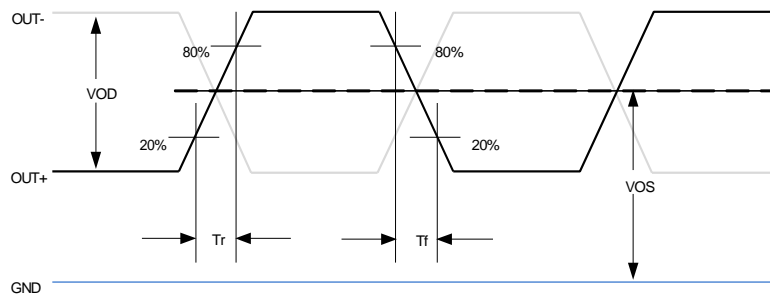
**Waveform Diagrams**



**Figure 1(a). LVPECL Voltage Levels per Differential Pin (OUT+/OUT-)**



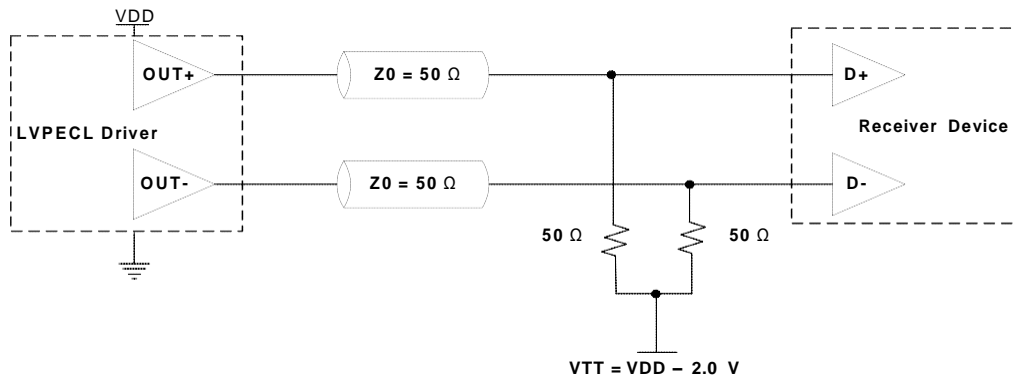
**Figure 1(b). LVPECL Voltage Levels Across Differential Pair**



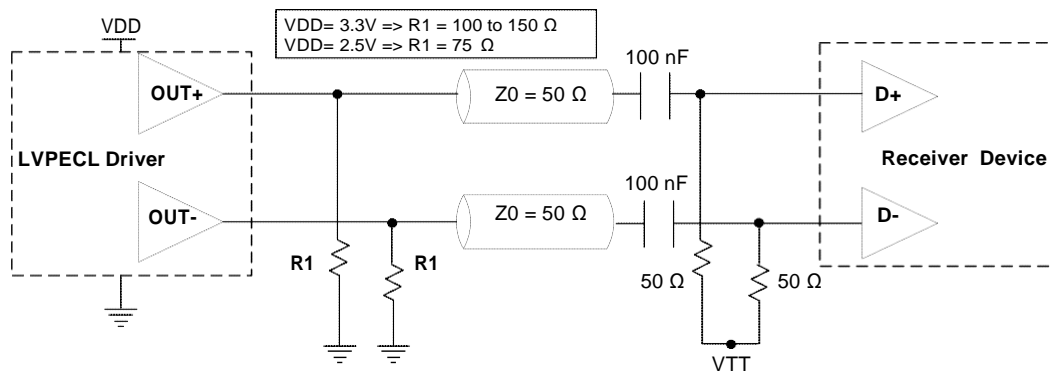
**Figure 2. LVDS Voltage Levels per Differential Pin (OUT+/OUT-)**

**Termination Diagrams**

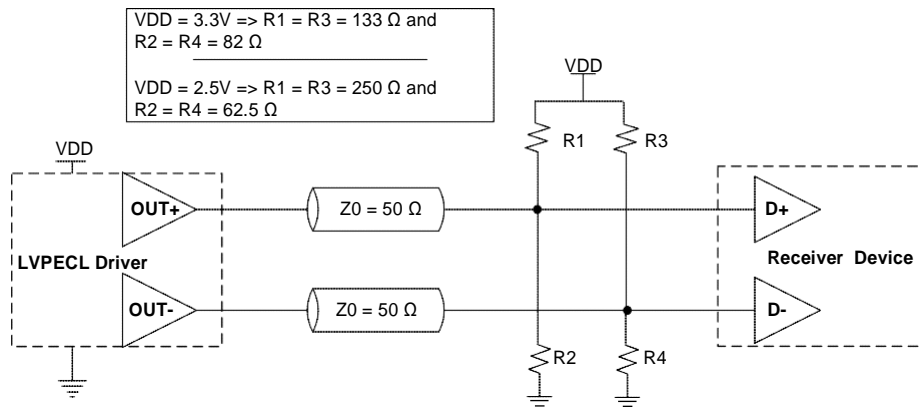
LVPECL:



**Figure 3. LVPECL Typical Termination**



**Figure 4. LVPECL AC Coupled Termination**



**Figure 5. LVPECL with Thevenin Typical Termination**

LVDS:

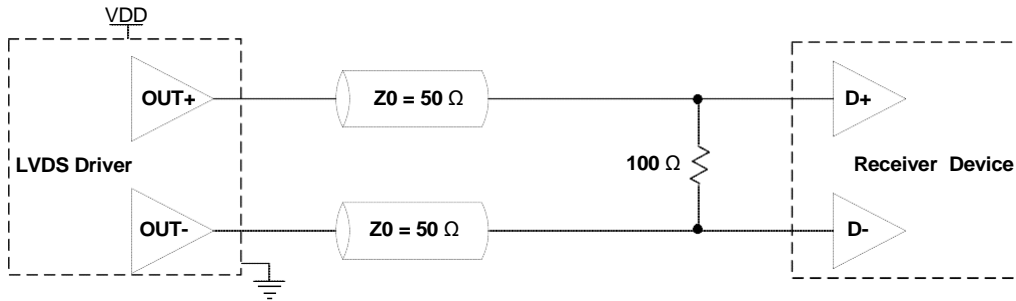


Figure 6. LVDS Single Termination (Load Terminated)

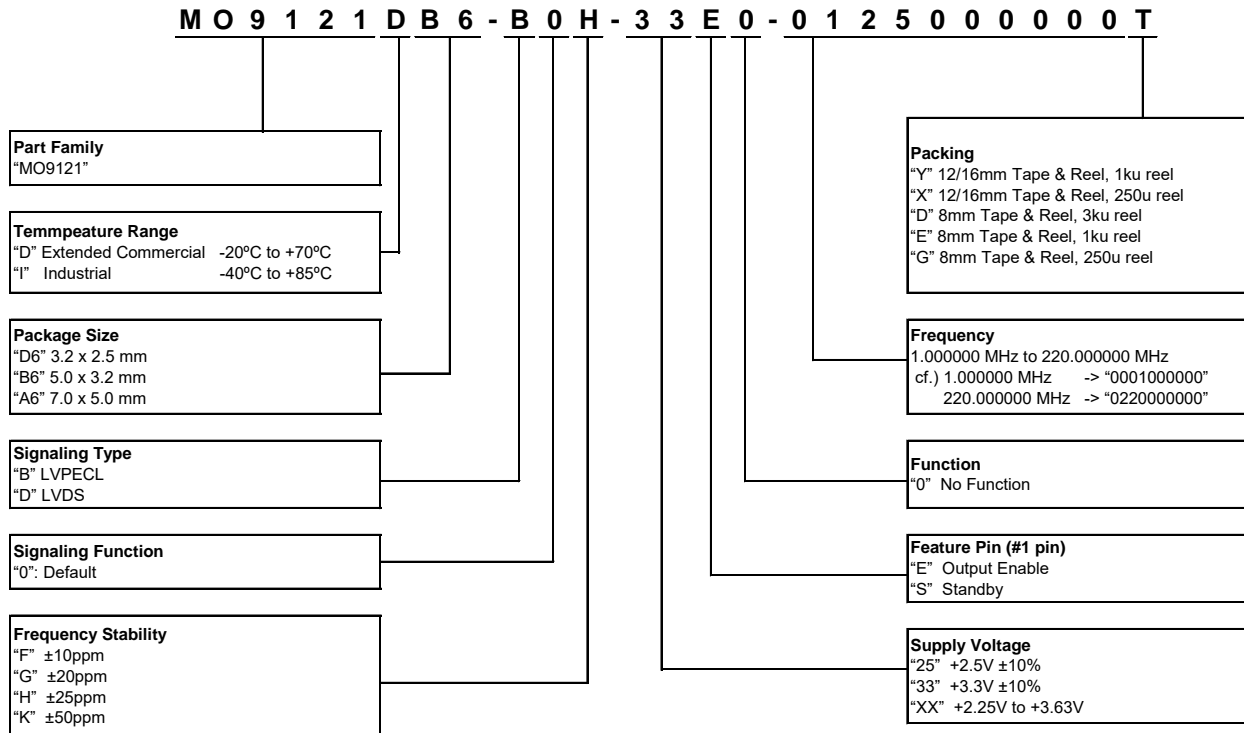
### Dimensions and Patterns

Package Size – Dimensions (Unit: mm) <sup>[1]</sup>	Recommended Land Pattern (Unit: mm) <sup>[2]</sup>
<p><b>3.2 x 2.5x 0.75 mm</b></p>	
<p><b>5.0 x 3.2 x 0.75 mm</b></p>	
<p><b>7.0 x 5.0x 0.90 mm</b></p>	

**Notes:**

1. Top Marking: Y denotes manufacturing origin and XXXX denotes manufacturing lot number. The value of “Y” will depend on the assembly location of the device.
2. A capacitor of value 0.1  $\mu$ F between V<sub>dd</sub> and GND is recommended.

### Ordering Information



### Ordering Codes for Supported Tape & Reel Packing Method

Device Size	8 mm T&R (3ku)	8 mm T&R (1ku)	8 mm T&R (250u)	12 mm T&R (1ku)	12 mm T&R (250u)	16 mm T&R (1ku)	16 mm T&R (250u)
7.0 x 5.0 mm	-	-	-	-	-	Y	X
5.0 x 3.2 mm	-	-	-	Y	X	-	-
3.2 x 2.5 mm	D	E	G	-	-	-	-

### Frequencies Not Supported

Range 1: From 209.000001 MHz to 210.999999 MHz

**Revision History**

Version	Release Date	Change Summary
1.01	2/20/13	Original
1.02	12/3/13	Added input specifications, LVPECL/LVDS waveforms, packaging T&R options
1.03	2/6/14	Added 8mm T&R option and $\pm 10$ ppm
1.04	4/8/14	Included 1.8V option for LVDS output only
1.05	7/30/14	Included Thermal Consideration table
1.06	10/20/14	Modified Thermal Consideration values. Preliminary removed from the title
1.07	1/4/16	Removed 1.8V option